

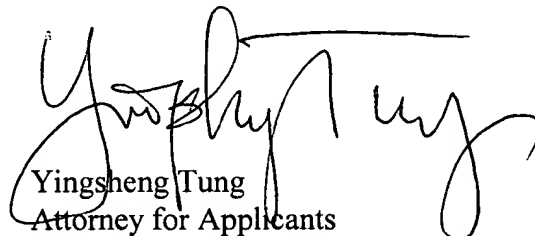
REMARKS/ARGUMENTS

Applicant thanks Examiner Kobert for his careful examination of the application and the clear explanation of the omission, the objection to the drawing and the claim rejections. In response, applicant amend the specification to add the reference to the related provisional application; amend claim 21 to overcome the 112 rejection to claim 21 and the objection to the drawing; amend claim 9 to overcome the 112 rejection; and claims 1 to overcome the 102 rejection. Detailed explanation follows.

1. Specification is amended to add reference to the related provisional application number 60/219,717 filed on July 14, 2001.
2. Claim 5 is amended to delete the phrase "such as a polyimide" to make the claim more definite without changing the scope.
3. Claim 9 is amended to replace "metal is" with "conductive leads are" to overcome the 112, second paragraph rejection to claim 9.
4. Claim 21 is amended to delete the phrase "composite plastic disc" to overcome the objection to the drawing figures and to overcome the 112, first paragraph rejection to claim 21.
5. Claim 1 is amended to add a limitation that requires the substrate to be formed of a material of which the coefficient of thermal expansion is similar to that of a semiconductor wafer. This limitation is fully supported in the original description of this application but is not disclose in the Turner reference, which discloses an apparatus for electrically connecting contact pads of two circuit boards.

In conclusion, applicants respectfully submit that the application as amended is in allowable form and the amendments the claims fully overcome the objections and the pending claims distinguish over the cited reference. Applicant respectfully requests further examination of this application and timely allowance of the pending claims.

Respectfully submitted,



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